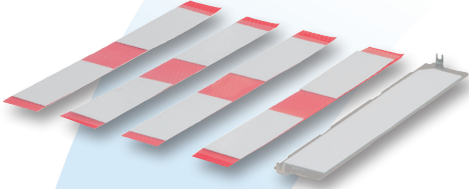


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THIN THERMALLY CONDUCTIVITY ELASTOMERIC INTERFACE MATERIAL

Tflex™ 200T V0 is a specially formulated thin gap filler thermal interface material designed for thin interfaces that require a combination good thermal performance with great reliability. The elastomeric property of Tflex™ 200T V0 provides good thermal performance in a thin interface where reliability, shock and vibration considerations, are critical performance considerations in addition to low thermal resistance.

Tflex™ 200T V0's unique silicone and ceramic filler technology allows a combination of great reliability, good thermal performance, and easy handling.

Tflex™ 200T V0 is slightly tacky, and requires no additional adhesive coating that inhibits thermal performance. Tflex™ 200T V0 is electrically insulating, stable from -40°C thru 200°C and meets UL 94V0 flame rating.

FEATURES AND BENEFITS

- Thermal Conductivity 1.5 W/mK
- Compliant Elastomeric based thin interface material
- Available in 0.008-inch (0.2mm), 0.010-inch (0.25mm), 0.012-inch (0.30mm), 0.015-inch (0.38mm) , and 0.020-inch (0.51mm) thicknesses
- Slightly tacky for adhesion during assembly and transport
- Competitive price for high volume applications
- Available as individual custom parts, sheets, or custom parts converted on a roll

APPLICATIONS

- Memory Modules:
DDR2, DDR3, SDRAM, SRAM, RAM, NVRAM
- LED solid state lighting
- Power electronics

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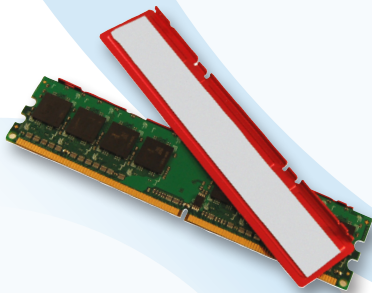
Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

| | 8 MIL | 10 MIL | 15 MIL | TEST METHOD |
|-------------------------------------|---|---|---|-----------------------|
| Construction & Composition | Ceramic filled silicone elastomer | Ceramic filled silicone elastomer | Ceramic filled silicone elastomer, reinforced | |
| Color | Light Grey | Light Grey | Light Grey | Visual |
| Thickness | 0.008" (0.203mm) | 0.010" (0.254mm) | 0.015" (0.381mm) | |
| Thickness tolerance | ±0.0015" (±0.038mm) | ±0.0015" (±0.038mm) | ±0.00225" (±0.057mm) | |
| Specific Gravity (Density) | 2.32 g/cc | 2.32 g/cc | 2.32 g/cc | Helium Pycnometer |
| Hardness (Shore 00) | 55 | 55 | 55 | ASTM D2240 |
| Outgassing TML (Post Cured) | 0.38% | 0.38% | 0.38% | ASTM E595 |
| Outgassing CVC (Post Cured) | 0.11% | 0.11% | 0.11% | ASTM E595 |
| UL Flammability Rating | 94 V0 | 94 V0 | 94 V0 | E180840 |
| Temperature Range | -45°C to 200°C | -45°C to 200°C | -45°C to 200°C | |
| Thermal Conductivity | 1.5 W/mK | 1.5 W/mK | 1.5 W/mK | Hot Disk |
| Thermal Impedance @ 10 psi @ 69 KPa | 0.384°C-in ² /W 2.48°C-cm ² /W | 0.488°C-in ² /W 3.14°C-cm ² /W | 0.714°C-in ² /W 4.60°C-cm ² /W | ASTM D5470 (modified) |
| Thermal Expansion (30-150°C) | 231.19ppm/°C | 231.19ppm/°C | 231.19ppm/°C | IPC-TM-650 2.4.2.4 |
| Volume Resistivity | 3.5x10 ¹⁰ ohm-cm | 3.5x10 ¹⁰ ohm-cm | 3.5x10 ¹⁰ ohm-cm | ASTM D257 |
| Dielectric Constant @ 1 MHz | 5.0 | 5.1 | 5.1 | ASTM D150 |

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.



THR-DS-Tflex-200T-V0 1209

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